10th week lectures: Benchmarking Nanoelectronics

Transistor AC properties

"Normal active" bias



• E-B forward bias $(V_b > V_e)$

• C-B reverse bias $(V_c > V_b)$

$$\circ$$
 I_{ce} = 100 I_{be}=bI_{be}

Like a diode.

Global dc properties



Note Early effect.

It is assumed you know this, so it is rare to see on data sheets!

http://www.toshiba.com/taec/components/Datasheet/2SA1244DS.pdf

ac properties: notation



We will use equivalent circuit #1 (implicitly).



Note: three terminal device has three-terminal equivalent ac circuit.





Note: three terminal device has three-terminal equivalent ac circuit.





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 g_{m}







If a control of the second of



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Rules for ac analysis

- From complete circuit, calculate dc currents and voltages
- For ac analysis only:
 - dc voltage source -> short circuit
 - dc current source -> open circuit
- Replace transistor with p or T-model
- Now solve (simplified) ac circuit

Next

Generalized y-parameters
not just common emitters

- Capacitances
- y-parameters from doping profile
- \circ Definition of f_{T}

If A Care of the step in a components, life can be simplified:



 V_c

 i_c

General admittance matrix Last lecture, we had emitter grounded. Called common emitter configuration:



Y-matrix has 9 elements, but once you know 4 you know them all because:

$$\label{eq:i_e} \begin{split} i_e &= i_b + i_c \\ \text{and:} \\ v_{cb} + v_{be} = v_{ce} \end{split}$$

See book about details procedure to get 9 parameters from only 4.

Three configuration (Ve=0):

$$\begin{pmatrix} i_b \\ i_c \end{pmatrix} = \begin{pmatrix} y_{bb} & y_{bc} \\ y_{cb} & y_{cc} \end{pmatrix} \begin{pmatrix} v_b \\ v_c \end{pmatrix} = \begin{bmatrix} y \end{bmatrix}_e \begin{pmatrix} v_b \\ v_c \end{pmatrix}$$

Common base configuration ($v_b=0$):

$$\begin{pmatrix} i_e \\ i_c \end{pmatrix} = \begin{pmatrix} y_{ee} & y_{ec} \\ y_{ce} & y_{cc} \end{pmatrix} \begin{pmatrix} v_e \\ v_c \end{pmatrix} = \begin{bmatrix} y \end{bmatrix}_b \begin{pmatrix} v_e \\ v_c \end{pmatrix}$$

Common collector configuration ($v_c=0$):

$$\begin{pmatrix} i_b \\ i_e \end{pmatrix} = \begin{pmatrix} y_{bb} & y_{be} \\ y_{eb} & y_{ee} \end{pmatrix} \begin{pmatrix} v_b \\ v_e \end{pmatrix} = \begin{bmatrix} y \end{bmatrix}_c \begin{pmatrix} v_b \\ v_e \end{pmatrix}$$

Easiest to calculate from doping profile.

Generalized p model: Regardless of which configuration you use, the following p model applies:

$$\begin{pmatrix} i_1 \\ i_2 \end{pmatrix} = \begin{pmatrix} y_{11} & y_{12} \\ y_{21} & y_{22} \end{pmatrix} \begin{pmatrix} v_1 \\ v_2 \end{pmatrix}$$



Common emitter: 1=base, 2=collector Common base: 1=emitter, 2=collector Common collector: 1=base, 2= emitter

You might be used to V=IR

General impedance matrix



Y-matrix has 9 elements, but once you know 4 you know them all because:

h matrix:

 $\begin{pmatrix} v_1 \\ i_2 \end{pmatrix} = \begin{pmatrix} h_{11} & h_{12} \\ h_{21} & h_{22} \end{pmatrix} \begin{pmatrix} i_1 \\ v_2 \end{pmatrix}$

Common emitter: 1=base, 2=collector Common base: 1=emitter, 2=collector Common collector: 1=base, 2= emitter

Note: In general, matrix elements depend on dc currents, dc voltages, and frequency. Spec. sheet (or model) will provide the matrix elements as a table vs. frequency, usually for only one bias current. Common emitter h matrix:

$$\begin{pmatrix} v_b \\ i_c \end{pmatrix} = \begin{pmatrix} h_{11e} & h_{12e} \\ h_{21e} & h_{22e} \end{pmatrix} \begin{pmatrix} i_b \\ v_c \end{pmatrix}$$

- Early effect: Collector voltage changes current gain (b).
- b depends on frequency and collector voltage.
- How do we define frequency at which b = 1?
- At $v_c=0$. This is h_{21e}

$$i_c = h_{21e}i_b + h_{22e}v_c \longrightarrow h_{21e}i_b$$

• We define f_T such that:

$$\left|h_{21e}\right|(f_T) = 1$$

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- •Circuit model good only for low frequencies
- •At high frequencies computer must be used!
- •That concludes our derivation of intrinsic HBT behavior.
- •Next will include parasitics, and discuss f_T , f_{max}



Parasitics f_T, f_{max}



Circuit model good only for low frequenciesAt high frequencies computer must be used!

Hybrid p model:

simplified:





S_naramatare

TOSHIBA

2SA1245



This is what you see on data sheets. Related to input impedance, output impedance and gain vs. frequency.

=> Need to discuss ac performance.

Summary of parameters

- Impedance matrix (V=IR -> V=IZ)
- Admittance matrix (I=YV)
- h-matrix (combination)
- ABCD matrix (combination)
- S-matrix (microwave reflections and transmissions)

"If you know one, then you know them all..." See Liu, page 249 for conversions.

Measurement techniques





Λ

Cost (rough estimates)

10 GHz: \$50,000
20 GHz: \$70,000
40 GHz: \$90,000
110 GHz: \$250,000
> 110 GHz: very expensive

For cost and difficulty reasons, parameters of transistor not always measure all the way up to f_T , but extrapolated.

These are only estimates. Contact vendor for actual prices.



Fig. 14. Gains of a $0.4 \,\mu\text{m} \times 6 \,\mu\text{m}$ emitter and $0.7 \,\mu\text{m} \times 10 \,\mu\text{m}$ collector HBT fabricated using electron-beam lithography. Theoretical $-20 \,\text{dB/decade} (H_{21}, U)$ gain slopes are indicated. The device exhibits an *extrapolated* 1.08 THz f_{max} .

From Rodwell, et al, TRANSACTIONS ON ELECTRON DEVICES 48 (11): 2606-2624 IEEE NOV 2001 EECS 277C Nanotechnology © 2015 P. Burke


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Ohmic contact

Specific contact resistance typically 10⁻⁶ ohm-micron² (Discuss on board.)

$$R_{EE} = \frac{\rho_{\sigma E}}{A_E} = \frac{\rho_{\sigma E}}{L_E W_E}$$

For a distributed contact, thinks are a little more complicated. (Draw distributed RC network on board, discuss.) A solution is:

$$R_{BB} = \frac{\sqrt{R_{SHB}}\rho_{\sigma B}}{L_E} \operatorname{coth}\left(W_B \sqrt{\frac{R_{SHB}}{\rho_{\sigma B}}}\right)$$

 R_{SHB} is R per square (discuss)



$$R_{E(epi)} = \rho_{E(epi)} \frac{X_{E(epi)}}{L_E W_E}$$

(discuss)

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$$R_{Bx(epi)}$$
 (discuss)



$$R_{E(epi)} = \rho_{E(epi)} \frac{X_{E(epi)}}{L_E W_E}$$

(discuss)

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Parasitics: In summary



Total parasitics include contact, epi, and metal layer resistance. Sometimes inductance also added in.

$$\begin{pmatrix} v_b \\ i_c \end{pmatrix} = \begin{pmatrix} h_{11e} & h_{12e} \\ h_{21e} & h_{22e} \end{pmatrix} \begin{pmatrix} i_b \\ v_c \end{pmatrix}$$

- Early effect: Collector voltage changes current gain (b).
- b depends on frequency and collector voltage.
- How do we define frequency at which b = 1?
- At $v_c=0$. This is h_{21e}

$$i_c = h_{21e}i_b + h_{22e}v_c \longrightarrow h_{21e}i_b$$

• We define f_T such that:

$$\left|h_{21e}\right|(f_T) = 1$$

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$$f_{T} = \frac{1}{2\pi\tau_{ec}}$$

$$\tau_{ec} = \tau_{e} + \tau_{b} + \tau_{sc} + \tau_{c}$$



Time to charge up junction capacitors.



Time to charge up base minority carriers. Or: time to diffuse from emitter to collector. (Built in field helps a lot here.)



Or: time to *drift* through space charge of base-collector junction.



Time to charge collector junction capacitor through parasitic resistors.

$$f_{T}: \qquad \begin{pmatrix} v_{b} \\ i_{c} \end{pmatrix} = \begin{pmatrix} h_{11e} & h_{12e} \\ h_{21e} & h_{22e} \end{pmatrix} \begin{pmatrix} i_{b} \\ v_{c} \end{pmatrix}$$

"It can be shown that..."
$$h_{21e} = \frac{\alpha_{T0}}{(1 - \alpha_{T0}) + i(f / f_{T})} \quad \alpha_{T0} \equiv 1 - \frac{X_{B}^{2}}{2L_{n}^{2}}$$

Discuss rolloff, low frequency value.

max

In real circuits, we do not want to short circuit the output! Unilateral power gain: if impedance matching network is set up so that there is no reverse transmission ($S_{12}=0$), in that case the power gain is called the *unilateral power gain*.

"It can be shown that..."

$$U = \frac{|z_{21} - z_{12}|^2}{4[\operatorname{Re}(z_{11})\operatorname{Re}(z_{22}) - \operatorname{Re}(z_{12})\operatorname{Re}(z_{21})]}$$

"It can be shown that..."

$$U = \frac{\alpha_{T0}^2 \omega_T}{4 \operatorname{Re}(z_b) C_{jc} \omega^2}$$

2

$$f_{\rm max} = \sqrt{\frac{f_T}{8\pi r_b C_{jc}}}$$

Discuss r_b dependence, want heavily doped base. Need for *H*BT.

Field Effect Devices

- MOSFET
- JFET
- MESFET
- HEMT



- •Gate has high input resistance (10¹² W)
- •Si covered in ECE 277A.
- •No oxide for GaAs, so need different type of device.

Non-oxide transistors

- JFET: Junction Field Effect Transistor
- MESFET: Metal Electron Semiconductor Field Effect Transistor
- HEMT: High Electron Mobility Transistor
 - Also called:
 - MODFET Modulation Doped Field Effect Transistor
 - TEGFET Two-Dimensional Electron Gas Field Effect Transistor
 - pHEMT Pseudomorphic HEMT
 - HFET Heterojunction Field Effect Transistor

Integrating:

$$I_{D} = \mu \cdot C_{ox} (V_{GS} - V_{T} - V_{CS}(x)) \cdot \frac{\partial V_{CS}(x)}{\partial x} \cdot W$$

$$\int_{0}^{L} I_{D} dx = \int_{0}^{L} \mu \cdot C_{ox} (V_{GS} - V_{T} - V_{CS}(x)) \cdot \frac{\partial V_{CS}(x)}{\partial x} \cdot W dx$$

$$= \int_{V_{CS}(0)}^{V_{CS}(L)} \mu \cdot C_{ox} (V_{GS} - V_{T} - V_{CS}(x)) \cdot \partial V_{CS}(x) \cdot W = doable$$

$$I_D = \frac{W \cdot \mu \cdot C_{ox}}{L} \left[(V_{GS} - V_T) V_{DS} - \frac{V_{DS}^2}{2} \right]$$

FET I-V curves



 I_{DS}

Velocity saturation



 $v = \mu \cdot E$ $\longrightarrow v_{sat}$

From Shur, Physics of Semiconductor Devices

FET AC properties



This is the common-source Y-matrix. You can get all the matrices from it.

What about capacitances?

Book sticks to long channel devices, well below transit time frequency.

Modern devices are short and f_T is the transit time frequency.



C_{gs} dominates.

Hybrid p model:



When current flowing through capacitor is equal m_{gs}

then the frequency is f_T .

$$i_{g} = v_{gs} \left(\omega C_{gs} \right) \qquad i_{d} = g_{M} v_{gs}$$

At $f_{T} \qquad g_{M} v_{gs} = v_{gs} \left(\omega_{T} C_{gs} \right)$
 $\Rightarrow \omega_{T} = \frac{g_{M}}{C_{gs}} \Rightarrow f_{T} = \frac{g_{M}}{2\pi C_{gs}}$

 f_{T}



$$f_T = \frac{g_M}{2\pi C_{gs}}$$

In HW#6, you will prove for the long-channel device:

$$g_{M} = \frac{W\mu C_{ox}}{L} (V_{GS} - V_{T})$$
$$C_{ox} \sim C_{gs} / (LW)$$
$$f_{T} \rightarrow \frac{1}{2\pi} \frac{\mu (V_{GS} - V_{T})}{L^{2}}$$

For a short-channel device,

$$g_M = v_{sat} W C'_{ox}$$

$$f_T \rightarrow \frac{v_{sat}}{2\pi L} = \frac{1}{2\pi \tau_{tr}}$$

So book model is only good for frequencies much less than f_T .



Non-quasi static model:

Hybrid p model:





 \mathcal{V}_d

 i_d

Non-quasi static model in saturation:

Hybrid p model:

 \mathcal{V}_d

 i_d



g

i_g

Parasitics: Gate resistance: $R_g = \frac{1}{3} \frac{W}{L} R_{square}$



g

i_g

Parasitics: Source/Draina resistance:



 \mathcal{V}_d i_d

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g

i_g



f_{MAX}

$$f_{MAX} = \sqrt{\frac{f_T}{8\pi R_G C_{gd,t} \left[1 + \left(\frac{2\pi f_T}{C_{gd,t}}\right)\Psi\right]}}$$

$$\Psi \equiv (R_S + R_D) \frac{C_{gg,t}^2 g_d^2}{g_m^2} + (R_S + R_D) \frac{C_{gd,t} C_{gg,t} g_d}{g_m} + \frac{C_{gg,t}^2 g_d}{g_m^2}$$

 f_{max} helped by fingers. f_{T} not helped by fingers. fMax sometimes larger, sometimes smaller than f_{T} .



Fig. 1. Evolution of the record cutoff frequency $f_{\rm T}$ and the record maximum frequency of oscillation $f_{\rm max}$ of RF Si MOSFETs versus time. F. Schwierz and J. J. Liou, "RF Transistors: Recent Developments and Roadmap toward Terahertz Applications", *Solid-State Electronics*, **51**, **1079-1091**, (2007).


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F. Schwierz and J. J. Liou, "RF Transistors: Recent Developments and Roadmap toward Terahertz Applications", *Solid-State Electronics*, *51*, *1079-1091*, *(2007)*.



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